

INTERNATIONAL STANDARD



Printed electronics –
Part 202-9: Materials – Conductive ink – Printed patterns for mechanical test

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED ELECTRONICS –

**Part 202-9: Materials – Conductive ink –
Printed patterns for mechanical test**

FOREWORD

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The text of this International Standard is based on the following documents:

Draft	Report on voting
119/435/FDIS	119/449/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at www.iec.ch/publications.

A list of all parts in the IEC 62899 series, published under the general title *Printed electronics*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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INTRODUCTION

Printing processes are highly promising technologies for the fabrication of flexible electronics such as flexible displays, sensors, batteries, printed circuit boards, etc. During their lifetime, flexible printed electronics can experience various mechanical deformations in random directions such as bending, torsion, creasing, and rolling. Repeated mechanical deformations lead to significant stress and can cause the failure of flexible electronics products. Therefore, a standard test method to evaluate the mechanical reliability of flexible printed electronics is recommended. Mechanical test methods for final products such as flexible displays, sensors, and batteries are recommended in the industry. Moreover, a mechanical test for printed circuits and printed devices is recommended because the printing materials will be used and commercialized as basic components to develop the final printed electronics.

To test the mechanical reliability of printed circuits and printed devices, a proper mechanical test method and a standard pattern are recommended. Several mechanical test methods for flexible printed electronics such as the bending test, rolling test, and torsion test are already proposed in IEC. These previous methods suggested mechanical test methods but they focused on measuring the device reliability of the final product such as the flexible display, sensor, and battery rather than the reliability of each component. Therefore, to test the mechanical reliability of printed circuits and printed devices, standard printed patterns are required to perform mechanical tests.

In this document, basic conductive traces and features of printed patterns are proposed for mechanical tests. The standard pattern in this document can be a useful guideline to test the mechanical reliability of new materials for flexible printed electronics. The information obtained by using the standard patterns in this document will be beneficial to the ink suppliers to figure out the best use of their ink and to the users to improve the reliability of their products.

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PRINTED ELECTRONICS –

Part 202-9: Materials – Conductive ink – Printed patterns for mechanical test

1 Scope

This part of IEC 62899 describes basic patterns to evaluate the electrical reliability of a conductive layer under mechanical deformation. Using the standard pattern described in this document, the comparison of the electrical reliability of a conductive layer under mechanical deformation is possible when the sample dimension is identical.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62899-202, *Printed electronics – Part 202: Materials – Conductive ink*

IEC 62899-201, *Printed electronics – Part 201: Materials - Substrate*

IEC 62899-202-5, *Printed electronics – Part 202-5: Materials - Conductive ink – Mechanical bending test of a printed conductive layer on an insulating substrate*

IEC 62899-502-1, *Printed electronics – Part 502-1: Quality assessment – Organic light emitting diode (OLED) elements – Mechanical stress testing of OLED elements formed on flexible substrates*

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <https://www.electropedia.org/>
- ISO Online browsing platform: available at <https://www.iso.org/obp>

3.1

conductive ink

fluid intended for printing in which one or more molecules, polymers, or particles are dissolved or dispersed, and which becomes an electrically conductive layer by post treatment such as heating, UV and IR curing

[SOURCE: IEC-62899-202:2016, 3.2, modified – “intended for printing” and “UV and IR curing” have been added.]

3.2

bending test

deformation test by application of external stress perpendicular to the plane of a printed element

[SOURCE: IEC-62899-101:2019, 3.12]

3.3

torsion test

action of twisting a system, device or substrate, by subjecting one end of the specimen to a torsional load, while the other end is held in place, or rotated in the opposite direction

[SOURCE: IEC-62899-101:2019, 3.140, modified – the note has been removed.]

3.4

rolling test

test for measuring the endurance of a flexible printed electronics system while or after rolling and unrolling it onto and from a cylindrical roller with a specified radius

[SOURCE: IEC-62899-101:2019, 3.114, modified – the note has been removed.]

4 Standard environmental conditions

Standard atmospheric conditions for measurement shall apply as specified in IEC 62899-202:

- a) temperature: (23 ± 2) °C;
- b) relative humidity: (50 ± 10) %; in case of paper substrate: (50 ± 2) %.

5 Mechanical test methods

The mechanical test methods for printed patterns shall be in accordance with the following:

- a) bending test: IEC 62899-201, IEC 62899-202-5, IEC 62899-502-1;
- b) torsion test: IEC 62899-502-1;
- c) rolling test: IEC 62899-502-1.

6 Printed patterns for mechanical test

6.1 General

To test the mechanical reliability of a conductive layer, a proper mechanical test method and a standard pattern are necessary. Depending on the mechanical deformations such as bending, torsion, and rolling, the mechanical reliability of the printed pattern can be different. Therefore, standard patterns for each mechanical test method are proposed in this document. According to the printing technique used, such as inkjet printing, screen printing, or gravure printing, the width of the pattern can be selected. The tolerance of the sample length and width is ± 1 mm. The tolerance of the printed pattern length and width shall be ± 10 %. In this document, the representative dimensions widely used in the printing process are suggested as the printing pattern for the mechanical test. During mechanical testing, damage formation in the grip part shall be avoided. For in situ measurement of electrical resistance, the pad area can be used as a grip part, but the line area shall not be included in the grip part. For an ex situ test which measures electrical resistance before and after the mechanical test or at regular intervals, the user can modify the pad size and add extra space at the edge of the sample for stable grip during mechanical test.

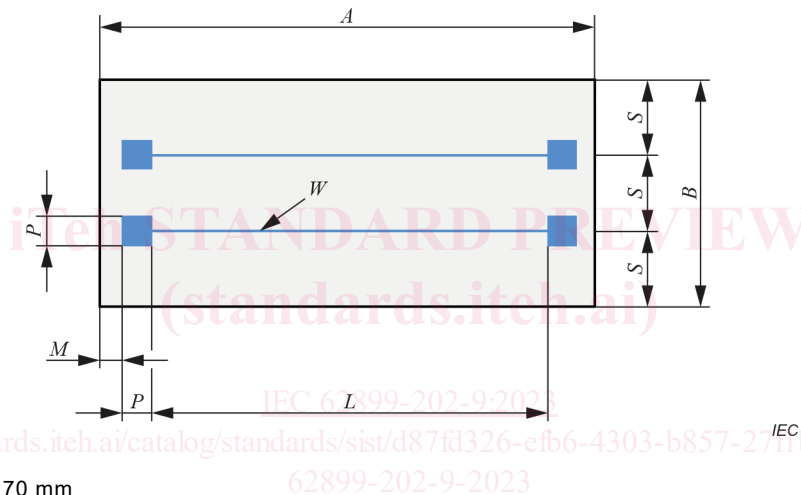
6.2 Patterns for bending test

6.2.1 General

Bending test methods for printed electronics are specified in IEC 62899-201, IEC 62899-202-5, and IEC 62899-502-1. For the bending test, the size of the sample and of the printed pattern, and the pattern direction are important factors in mechanical reliability. In this document, a basic line pattern and directional pattern are proposed. For electrical measurement, each end of the pattern may include a conductive pad with a square shape for probe contact. Several patterns may be printed together on one substrate for multiple measurements. A pad size (P) of 1 mm to 5 mm is allowed by the user. The margin area, M (0 mm to 5 mm), at the edge of the sample can be included in the sample to avoid additional stress during sample gripping.

6.2.2 Printed patterns for bending test

The dimensions of the printed pattern and sample for the bending test are shown in Figure 1.



A (sample length): 70 mm

B (sample width): 10 mm to 30 mm

L (pattern length): $L = A - 2 \times (P + M)$

M (margin area): 0 mm to 5 mm

S (space): $B/3$

P (pad size): 1 mm to 5 mm

W (pattern width): 0,01 mm to 3 mm (selected according to the printing technique)

Figure 1 – Printed patterns for bending test

6.2.3 Directional patterns for bending test

According to the direction between the printed patterns and bending directions, the mechanical reliability can be changed significantly. The patterns for testing the directional property of the conductive layer are shown in Figure 2. The patterns shall be located at the bending part of the test machine. By changing the angle between the bending direction and pattern direction, the electrical resistance change as a function of the angle can be measured. The pattern angles of 0° and 90° shall be tested, but other angles such as 30° , 45° , and 60° are optional.